

# **MMBF5434**

### **N-Channel Switch**

- · This device is designed for digital switching applications where very low on resistance is mandatory.
- Sourced from Process 58.



1. Drain 2. Source 3. Gate

# **Absolute Maximum Ratings \*** T<sub>A</sub>=25°C unless otherwise noted

| Symbol                            | Parameter  | Value      | Units |
|-----------------------------------|--|------------|-------|
| $V_{DG}$                          | Drain-Gate Voltage                               | 25         | V     |
| $V_{GS}$                          | Gate-Source Voltage                              | -25        | V     |
| I <sub>GF</sub>                   | Forward Gate Current                             | 10         | mA    |
| T <sub>J</sub> , T <sub>stg</sub> | Operating and Storage Junction Temperature Range | -55 ~ +150 | °C    |

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Electrical Characteristics** $T_A=25^{\circ}C$ unless otherwise noted

| Parameter                         | Test Condition   | Min. | Max. | Units |
|-----------------------------------|--|------|------|-------|
| teristics                         |  | •    |      | •     |
| Gate-Source Breakdwon Voltage     | $I_G = -1.0 \mu A, V_{DS} = 0$   | -25  |      | V     |
| Gate Reverse Current              | $V_{GS} = -15V, V_{DS} = 0$  |      | 200  | nA    |
| Gate-Source Cutoff Voltage        | $V_{DS} = 5.0V, I_{D} = 3.0nA$   | -1.0 | -4.0 | V     |
| Drain Cutoff Voltag               | V <sub>DS</sub> = 5.0, V <sub>GS</sub> = -10V  |      | 200  | pА    |
| teristics                         |  | •    |      | •     |
| Zero-Gate Voltage Drain Current * | V <sub>DS</sub> = 15V, I <sub>GS</sub> = 0   | 30   |      | mA    |
| Drain-Source On Resistance        | $V_{DS} = 0, I_{D} = 10 \text{mA}$   |      | 10   | Ω     |
| al Characteristics                |  | •    |      | •     |
| Input Capacitance                 | $V_{DS} = 0$ , $V_{GS} = 10V$ , $f = 1.0MHz$   |      | 30   | pF    |
| Reverse Transfer Capacitance      | $V_{DS} = 0$ , $V_{GS} = 10V$ , $f = 1.0MHz$   |      | 15   | pF    |
| 1                                 | Gate-Source Breakdwon Voltage Gate Reverse Current Gate-Source Cutoff Voltage Drain Cutoff Voltag  teristics Zero-Gate Voltage Drain Current * Drain-Source On Resistance al Characteristics Input Capacitance |      |      |       |

Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2.0%

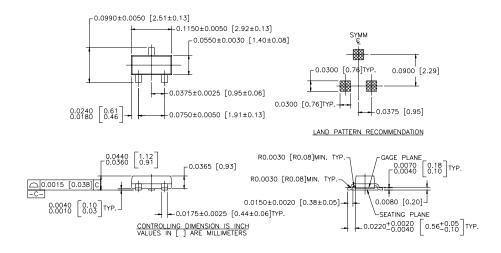
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| Thermal Characteristics T <sub>A</sub> =25°C unless otherwise noted |  |            |             |
|---|--|------------|-------------|
| Symbol  | Parameter                                  | Max.       | Units       |
| P <sub>D</sub>  | Total Device Dissipation Derate above 25°C | 350<br>2.8 | mW<br>mW/°C |
| $R_{\theta JC}$   | Thermal Resistance, Junction to Case       |            | °C/W        |
| $R_{\theta JA}$   | Thermal Resistance, Junction to Ambient    | 556        | °C/W        |

<sup>\*</sup> Device mounted on FR-4 PCB 1.6" × 1.6" × 0.06"

# **Package Dimensions**

# SuperSOT-3



Dimensions in Millimeters

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